

P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY

| V_{DS} (V) | $R_{DS(on)}$ (Ω) | I_D (A) | Q_g (Typ.) |
|--------------|-----------------------------|---------------------|--------------|
| - 30 | 0.173 at $V_{GS} = - 10$ V | - 0.98 ^a | 3.25 |
| | 0.243 at $V_{GS} = - 4.5$ V | - 0.83 | |

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

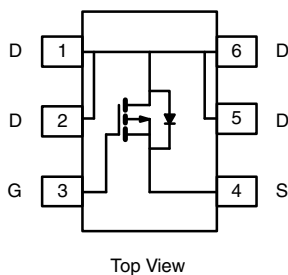


RoHS
COMPLIANT
HALOGEN
FREE

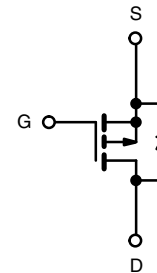
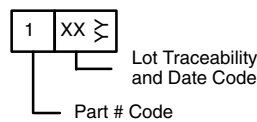
APPLICATIONS

- Load Switch

SC-89 (6-LEADS)



Marking Code



Ordering Information: Si1073X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|---|----------------|-------------|------------------------|
| Drain-Source Voltage | V_{DS} | - 30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | |
| Continuous Drain Current ($T_J = 150$ °C) ^a | $T_A = 25$ °C | I_D | - 0.98 ^{b, c} |
| | $T_A = 70$ °C | | - 0.78 ^{b, c} |
| Pulsed Drain Current | I_{DM} | - 8 | A |
| Avalanche Current | I_{AS} | - 6 | mJ |
| Repetitive Avalanche Energy | E_{AS} | 1.8 | |
| Continuous Source-Drain Diode Current | $T_A = 25$ °C | I_S | 0.2 ^{b, c} |
| Maximum Power Dissipation ^a | $T_A = 25$ °C | P_D | 0.236 ^{b, c} |
| | $T_A = 70$ °C | | 0.151 ^{b, c} |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to 150 | °C |

THERMAL RESISTANCE RATINGS

| Parameter | Symbol | Typical | Maximum | Unit |
|---|--------------|------------|---------|------|
| Maximum Junction-to-Ambient ^{b, d} | $t \leq 5$ s | R_{thJA} | 440 | °C/W |
| | Steady State | | 540 | |
| | | | 650 | |

Notes:

- Based on $T_C = 25$ °C.
- Surface mounted on 1" x 1" FR4 board.
- $t = 5$ s.
- Maximum under steady state conditions is 650 °C/W.

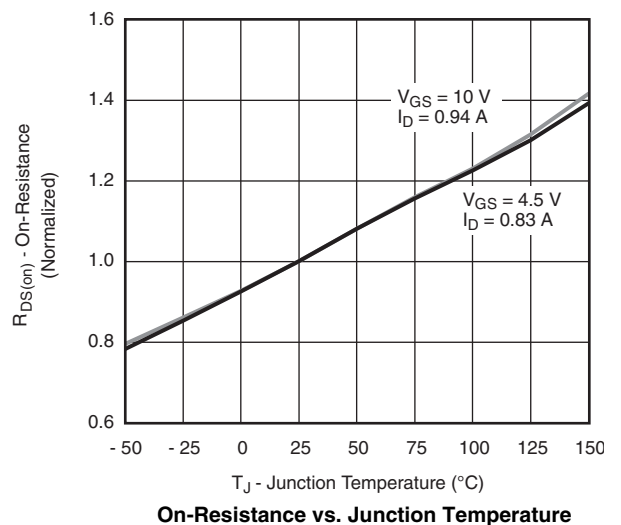
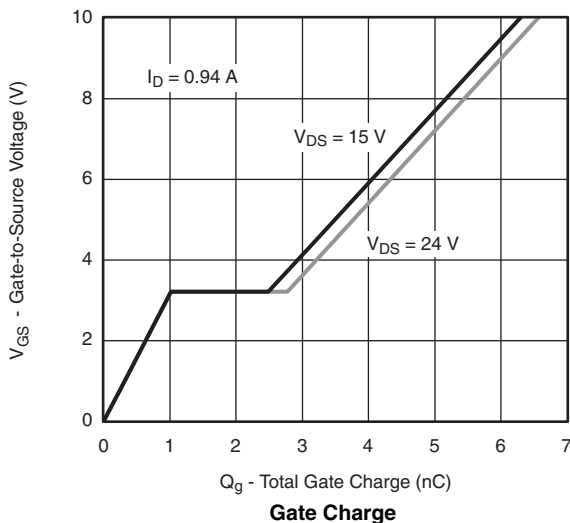
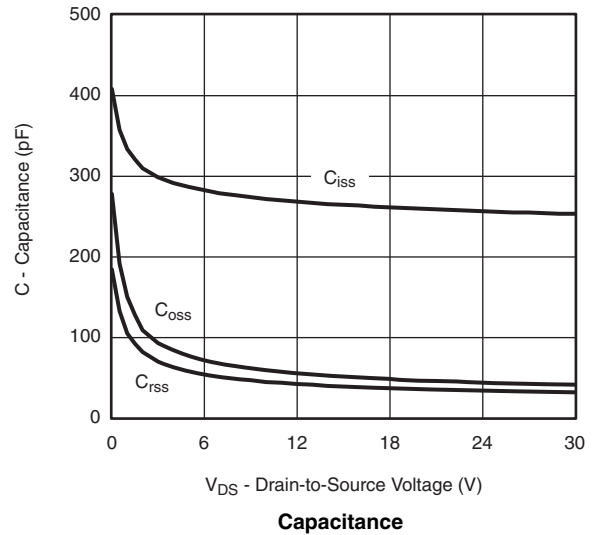
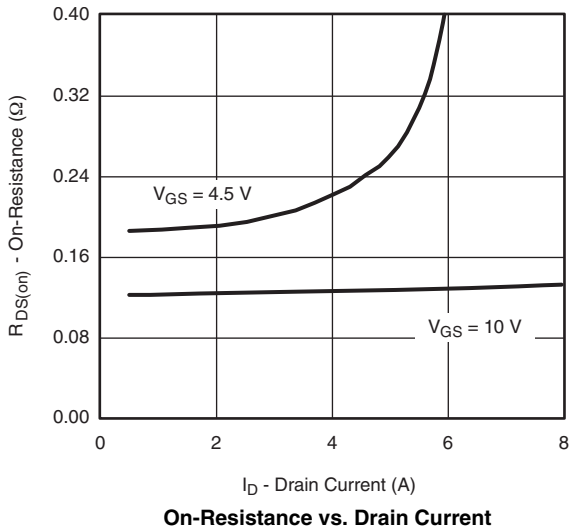
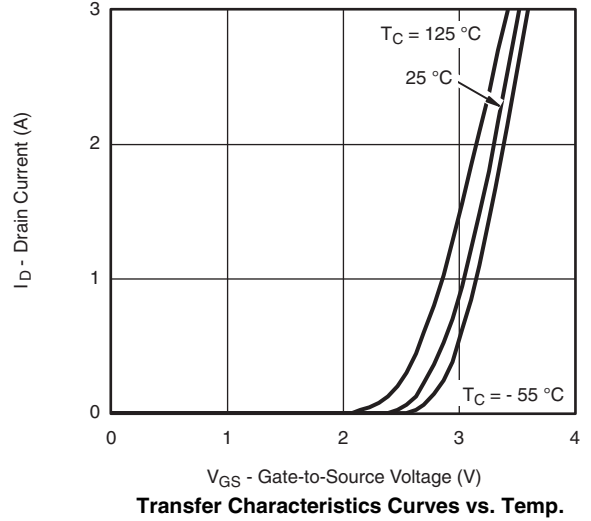
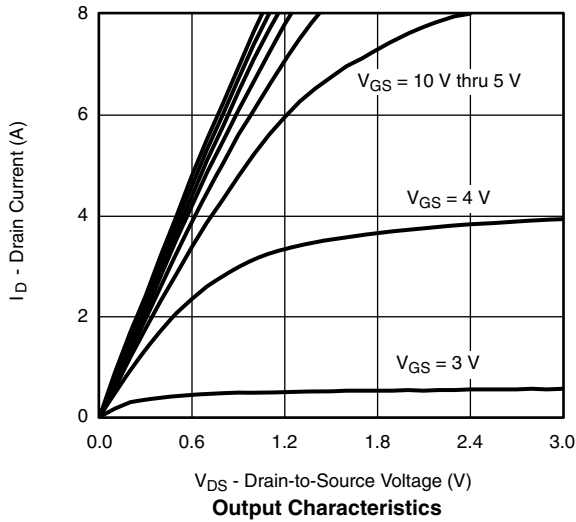
| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | |
|--|-------------------------|--|------|--------|-----------|----------------------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$ | - 30 | | | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | $I_D = -250\text{ }\mu\text{A}$ | | - 30.7 | | mV/ $^\circ\text{C}$ |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | 3.78 | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$ | - 1 | | - 3 | V |
| Gate-Source Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -30\text{ V}, V_{GS} = 0\text{ V}$ | | | - 1 | μA |
| | | $V_{DS} = -30\text{ V}, V_{GS} = 0\text{ V}, T_J = 85\text{ }^\circ\text{C}$ | | | - 10 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} \geq 5\text{ V}, V_{GS} = -10\text{ V}$ | - 8 | | | A |
| Drain-Source On-State Resistance ^a | $R_{DS(on)}$ | $V_{GS} = -10\text{ V}, I_D = -0.98\text{ A}$ | | 0.144 | 0.173 | Ω |
| | | $V_{GS} = -4.5\text{ V}, I_D = -0.83\text{ A}$ | | 0.202 | 0.243 | |
| Forward Transconductance | g_{fs} | $V_{DS} = -15\text{ V}, I_D = -0.98\text{ A}$ | | 3.52 | | S |
| Dynamic^b | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = -15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ | | 265 | | pF |
| Output Capacitance | C_{oss} | | | 51 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 39 | | |
| Total Gate Charge | Q_g | $V_{DS} = -15\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -0.98\text{ A}$ | | 3.25 | 4.88 | nC |
| | | $V_{DS} = -15\text{ V}, V_{GS} = -10\text{ V}, I_D = -0.98\text{ A}$ | | 6.3 | 9.45 | |
| Gate-Source Charge | Q_{gs} | | | 1.02 | | |
| Gate-Drain Charge | Q_{gd} | | | 1.47 | | |
| Gate Resistance | R_g | $f = 1\text{ MHz}$ | | 14 | 21 | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -15\text{ V}, R_L = 19.2\text{ }\Omega$ $I_D \cong -0.78\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$ | | 6 | 9 | ns |
| Rise Time | t_r | | | 10 | 15 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 14 | 21 | |
| Fall Time | t_f | | | 6 | 9 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -15\text{ V}, R_L = 22.72\text{ }\Omega$ $I_D \cong -0.66\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$ | | 26 | 39 | |
| Rise Time | t_r | | | 28 | 42 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 28 | 42 | |
| Fall Time | t_f | | | 12 | 18 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Pulse Diode Forward Current ^a | I_{SM} | | | | 8 | A |
| Body Diode Voltage | V_{SD} | $I_S = -0.63\text{ A}$ | | 0.8 | 1.2 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F = -0.7\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$ | | 14.3 | 21.45 | nC |
| Body Diode Reverse Recovery Charge | Q_{rr} | | | 12.16 | 18.25 | |
| Reverse Recovery Fall Time | t_a | | | 11.1 | | ns |
| Reverse Recovery Rise Time | t_b | | | 3.2 | | |

Notes:

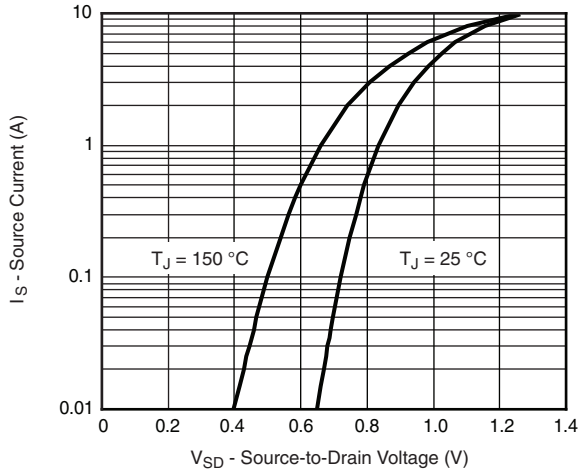
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

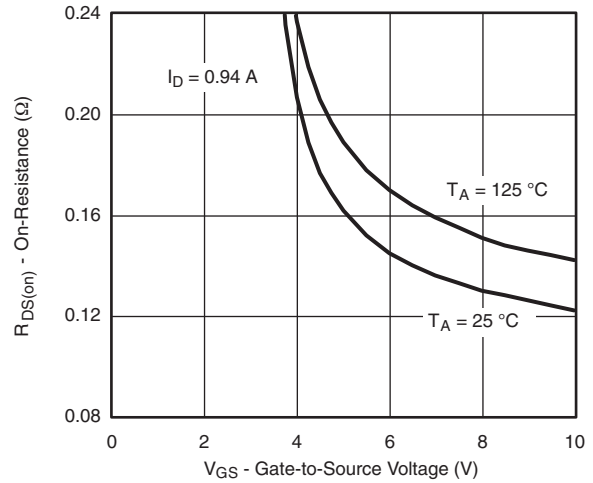
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



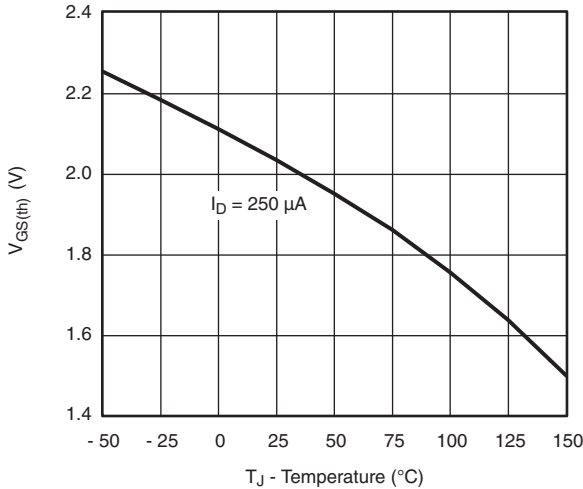
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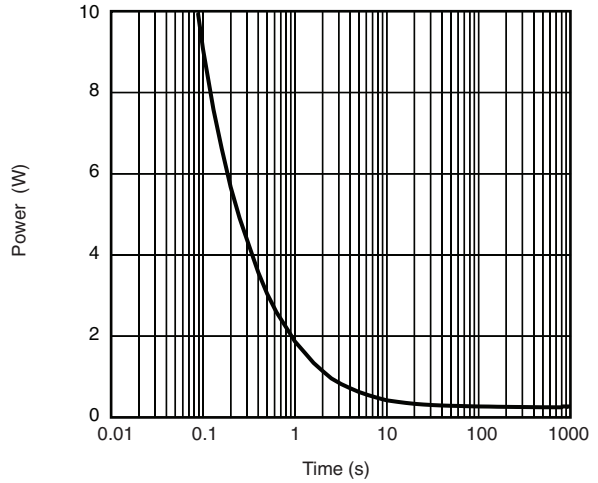
Source-Drain Diode Forward Voltage



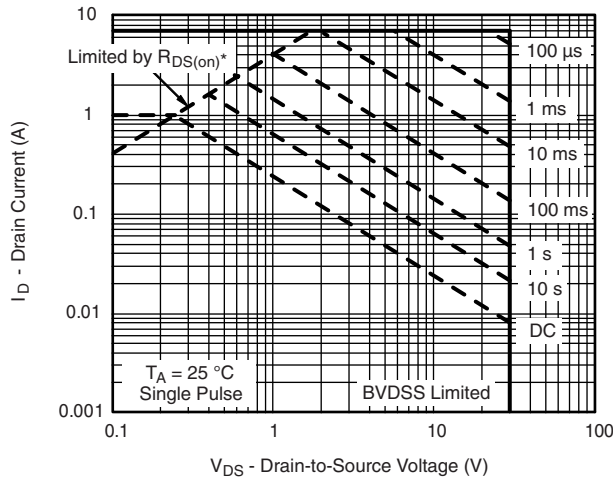
R_{DS(on)} vs. V_{GS} vs. Temperature



Threshold Voltage



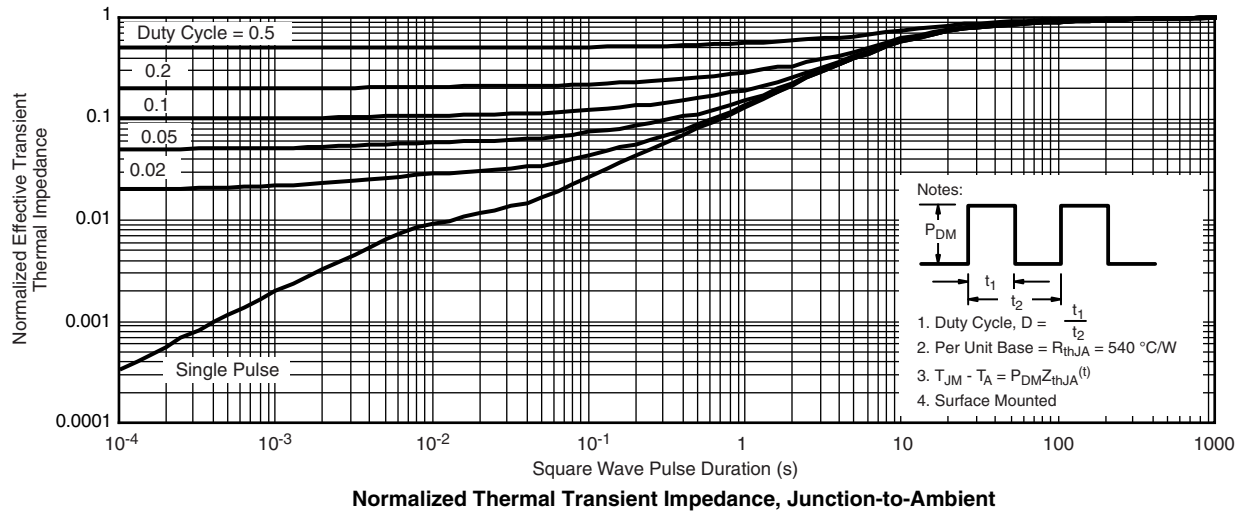
Single Pulse Power



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



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